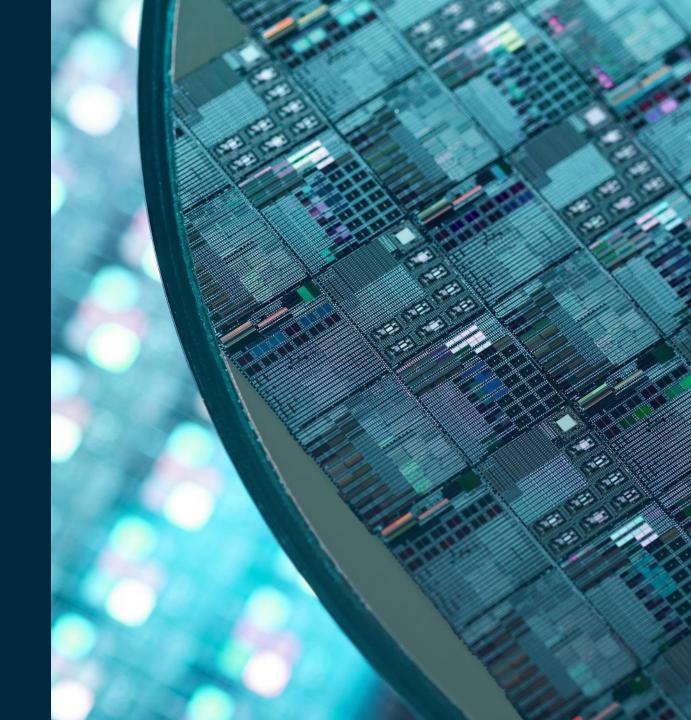


Exhibit Booth #8030

Strategies for Enabling Quantum
Development with Test & Measurement
from 77K down to milli-Kelvin

Jack DeGrave, PhD
Quantum Applications
THMA70



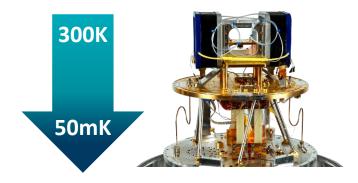
FormFactor At a Glance

WHO WE ARE



WHAT WE DO

CRYOGENIC TEST & MEASUREMENT



~\$762M 2,200+ PEOPLE



8,500+ LABS WORLDWIDE

TEST SERVICES

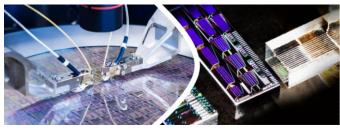
SUPERCONDUCTING DEVICES (4K, 50mK)



CMOS (4K, 77K) and COMPONENTS

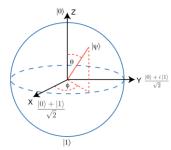


PHOTONIC DEVICES (4K, 50mK)



Quantum Computing Market Introduction

- Quantum computers are expected to solve problems that are unsolvable by classical computers
- Qubits instead of bits (superposition & entanglement)
- Application areas
 - Simulation of large molecules
 - Drug discovery
 - Financial modeling
 - Cybersecurity
 - And more...







Publicly Traded QC Companies







Quantum Computing Market Growth





Enabling Developers and Suppliers

Problem

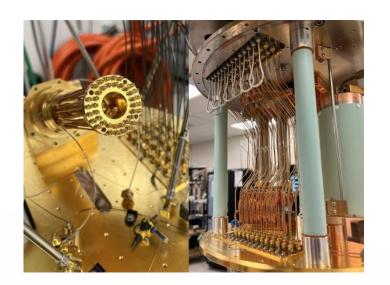
Cryogenic Test Equipment

High Capital Cost

Long lead time

- Limited Access to < 4 K and mK
- Slowed Development Cycles
- Poor Component Qualification





Solution

Cryogenic Test &

Measurement as a Service

Immediate Cryogenic Access

- Reduce R&D Risk
- Learn Design for Test
- Eliminate Barrier to Entry
- Prepare to Scale



Cryogenic Test & Measurement Services



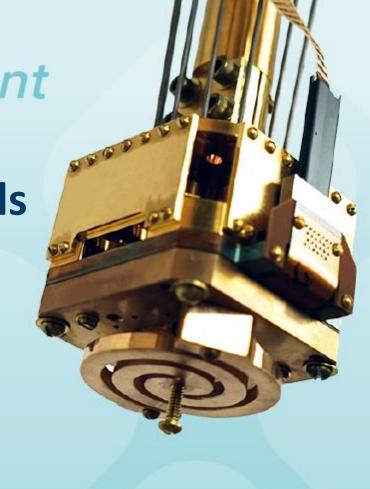




Accelerate Quantum Development



Advanced Cryogenic Lab



GRAND OPENING | DINNER AND TOUR



50 mK ADR Cryostat

Chip-Scale and Component Test Solution

Use Cases

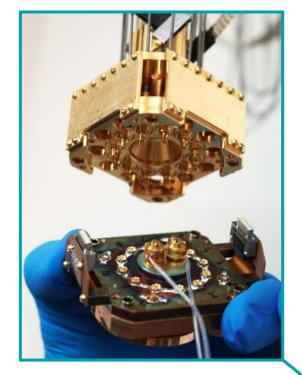
Developers

Qubit & Resonator Pre-characterization
Process Control
Materials Development

Vendors

Component Qualification
Performance Validation

PQ500 Probe Socket



Model 106 ADR Cryostat







2K

Photonic, Superconducting & Spin Qubits

Wafer Prober Solution for < 4 K, < 2 K

Use Cases

Statistical process control for scaling

4 K Nb resonators $(S_{11} \& S_{21})$

Josephson-Junction resistance

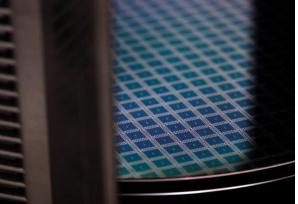
Machine learning models for qubit diagnostics

10 -5 -5 -5 -20 -5.98 6.03 6.08 6.13 6.18 6.23 6.28 6.33 6.38 6.43 Frequency (GHz)

IQ3000 Cryogenic Wafer Prober









HPD

4K Cryogenic Wafer Prober

Fully automated cryogenic wafer probing at 4K

Cryogen Control

- Warm Water Bath
- Vacuum pump with flow controller and pressure regulator
- Recirculation with Binary Gas Analyzer and a 3-way directional valve

Vision System

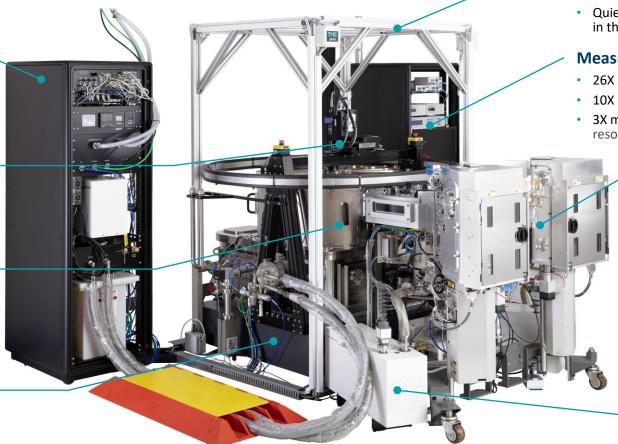
- 50 mm XYZ Travel
- <3 um resolving power
- Pneumatic lift and rotatable beam for easy servicing

Probe Station

- Gas spring assisted vacuum lid and latchable shield lids
- <4.5 K with 44 RF probes in contact
- +/- 112 mm XY, 0 13 mm Z, +/- 10°
 Theta motion

Rigid Construction

- A solid granite base with a rigid motion structure
- Allows for rapid die to die movement and fast settling times
- Up to 25 mm/s travel speed



Magnetic Cancellation

- Active cancellation with passive cryogenic shielding
- Quiescent magnetic field environment of <200 nT in the 4 K wafer space

Measurement and Control Electronics

- 26X system thermometers
- 10X 50 W heaters for rapid warmup in <8 hrs
- 3X magnetic probes with 0-200 uT range and 1 nT resolution

Wafer Cassette Loader

- Automated loading for 200 mm and 150 mm wafers
- Up to 25 wafer capacity
- <15 minute exchange time between wafers</p>

Vacuum Feedthroughs (Not Shown)

- Two large configurable vacuum flanges with additional smaller ports
- Large ports are 12 in x 18 in and 12 in x 26 in
- Base 56 RF (18 GHz) and 520 DC

Automated Pumping System

- Load lock isolated pumping systems for wafer loading while system is at base
- Full system pump down in <40 minutes



IQ3000 – Cryogenic Wafer Prober Details

Probe card installation



Wafer Exchange Cooldown

(X)

40

40

20

4

0:00

0:05

Timestamp

RF Feedthroughs



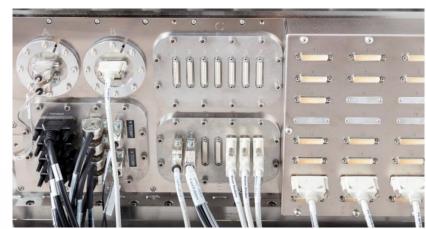
Wafer under probe card fixture



Chuck without wafer



Operational and DC feedthroughs



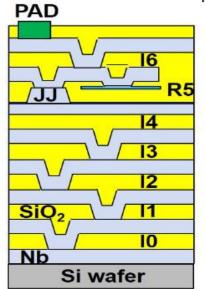


SFQ Device Characterization at 4K

of Devices = 24 SQUID-based Test Circuits

Test Method	Time to Measure at 4K
Conventional singulated die testing (dicing, wire bonding)	> 1 week
IQ3000 4K Cryogenic Wafer Prober with 200mm wafer	5 hours

https://arxiv.org/abs/2112.00705



M7 200 nm M6 200 nm

M5 135 nm M4 200 nm

M3 200 nm

M2 200 nm

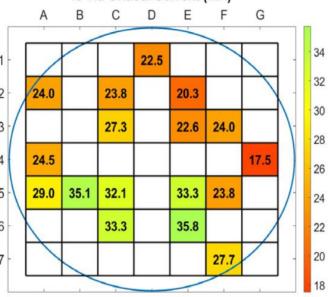
M1 200 nm

M0 200 nm

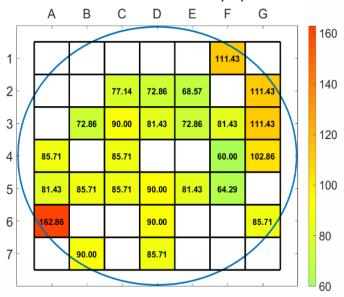
Characterization Measurements

- 1. SQUIF B field
- 2. Inductance/unit length
- 3. JJ critical current
- 4. Normal resistance
- 5. Gap current (V_g)

16 Via Critical Current (mA)



Measured SQIF B Field (nT)







Booth #8030



We're helping quantum developers and component suppliers speed up their time to data and improve development cycles.

www.FormFactor.com

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Jack DeGrave
Business Development

